

General Description

EMDT08N017RH uses high performance in on-state resistance, fast switching performance, and excellent quality.

These devices can also be utilized in industrial applications such as high power drives of E-Vehicles(E-bike), DC/DC converter and BMS, general purpose applications.

Features and benefits

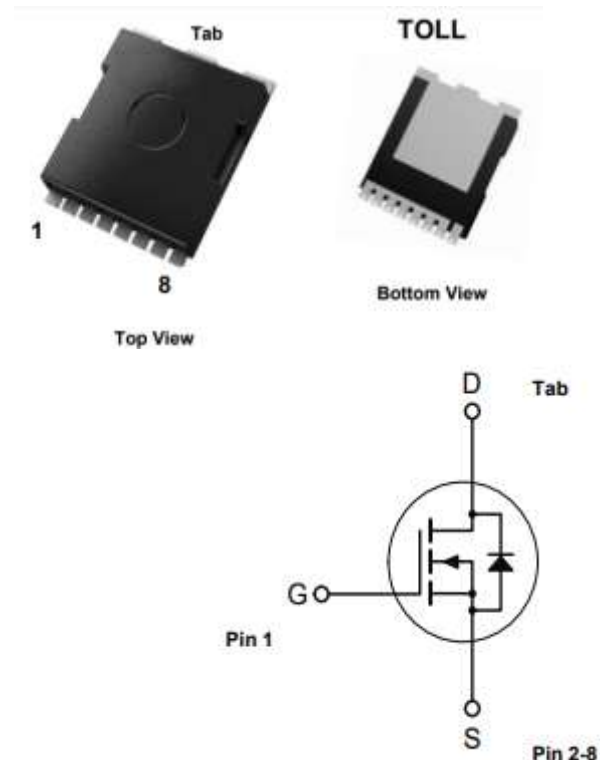
- Very low on-resistance RDS(on)
- 100% Avalanche / Rg / ΔV_{DS} Tested

Applications

- Motor Inverter
- Battery Management
- Power Inverter

Key performance parameters

V_{DS}	80	V
$R_{DS(on), max}$	0.0017	Ω
I_D	300	A
Q_G	183	nC
Junction temperature, max	175	$^{\circ}C$



Ordering information

Type / Ordering Code	Package	Marking	Packing	RoHS Status
EMDT08N017RH	TOLL	MDT08N017	Tape & Reel	Halogen Free



Single N-channel Trench MOSFET 80V 1.7mΩ 300A

EMDT08N17RH

Maximum Ratings

$T_A = 25^\circ\text{C}$, unless otherwise specified

Drain-source Voltage		V_{DS}	80	V
Gate-source Voltage		V_{GS}	± 20	V
Drain current	$T_C=25^\circ\text{C}$ Silicon Limited	I_D	340	A
	$T_C=25^\circ\text{C}$ Package Limited		300	A
	$T_C=100^\circ\text{C}$ Silicon Limited		240	A
¹⁾ Pulsed drain current	$T_C=25^\circ\text{C}$	I_{DM}	1200	A
Total power dissipation	$T_C=25^\circ\text{C}$	P_{tot}	469	W
	$T_C=100^\circ\text{C}$		234	W
²⁾ Avalanche energy, single pulse		E_{AS}	578	mJ
Operating and storage temperature		T_J, T_{stg}	- 55 ~ 175	$^\circ\text{C}$

Thermal characteristics

Thermal resistance, junction - case	$R_{\theta JC}$	0.32	K/W
³⁾ Thermal resistance, junction - ambient	$R_{\theta JA}$	40	K/W

Notes

1. Pulse width limited by T_{jmax}
2. EAS is tested at starting $T_J = 25^\circ\text{C}$, $L = 1.0\text{mH}$, $I_{AS} = 34\text{A}$, $V_{DD} = 50\text{V}$, $V_{GS} = 10\text{V}$
3. Surface mounted FR-4 board by JEDEC (jesd51-7)



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Electrical Characteristics (T_J = 25°C)

Static characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions / Note
Drain-source breakdown voltage	V _{(BR)DSS}	80	-	-	V	V _{GS} =0 V, I _D =250 μA
Gate threshold voltage	V _{GS(th)}	2.4	3.1	3.8	V	V _{DS} =V _{GS} , I _D =250 μA
Zero gate voltage drain current	I _{DSS}	-	-	1	μA	V _{DS} =80 V, V _{GS} =0 V
Gate-source leakage current	I _{GSS}	-	-	± 100	nA	V _{GS} =±20 V, V _{DS} =0 V
Drain-source on-state resistance	R _{DS(on)}	-	1.3	1.7	mΩ	V _{GS} =10 V, I _D =100 A
Gate resistance	R _G	-	3.0	-	Ω	f=1MHz
Transconductance	g _{fs}	-	120	-	S	V _{DS} =10 V, I _D =100 A

Dynamic characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions / Note
Input capacitance	C _{iss}	-	12,684	-	pF	V _{GS} =0 V, V _{DS} =40 V, f=1 MHz
Output capacitance	C _{oss}	-	2,338	-	pF	V _{GS} =0 V, V _{DS} =40 V, f=1 MHz
Reverse transfer capacitance	C _{rss}	-	65	-	pF	V _{GS} =0 V, V _{DS} =40 V, f=1 MHz
Turn-on delay time	t _{d(on)}	-	35	-	ns	V _{DD} =40 V, V _{GS} =10 V, I _D =100 A, R _{GS,ext} =3Ω
Rise time	t _r	-	27	-	ns	V _{DD} =40 V, V _{GS} =10 V, I _D =100 A, R _{GS,ext} =3Ω
Turn-off delay time	t _{d(off)}	-	132	-	ns	V _{DD} =40 V, V _{GS} =10 V, I _D =100 A, R _{GS,ext} =3Ω
Fall time	t _f	-	67	-	ns	V _{DD} =40 V, V _{GS} =10 V, I _D =100 A, R _{GS,ext} =3Ω

Gate charge characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions / Note
Gate to source charge	Q _{gs}	-	57	-	nC	V _{DD} =40 V, I _D =100 A, V _{GS} =0 to 10 V
Gate charge at threshold	Q _{gs(th)}	-	36	-	nC	V _{DD} =40 V, I _D =100 A, V _{GS} =0 to 10 V
Gate to drain charge	Q _{gd}	-	40	-	nC	V _{DD} =40 V, I _D =100 A, V _{GS} =0 to 10 V
Switching charge	Q _{sw}	-	61	-	nC	V _{DD} =40 V, I _D =100 A, V _{GS} =0 to 10 V
Gate charge total	Q _g	-	183	-	nC	V _{DD} =40 V, I _D =100 A, V _{GS} =0 to 10 V
Gate plateau voltage	V _{plateau}	-	4.7	-	V	V _{DD} =40 V, I _D =100 A, V _{GS} =0 to 10 V

Electrical characteristics diagrams

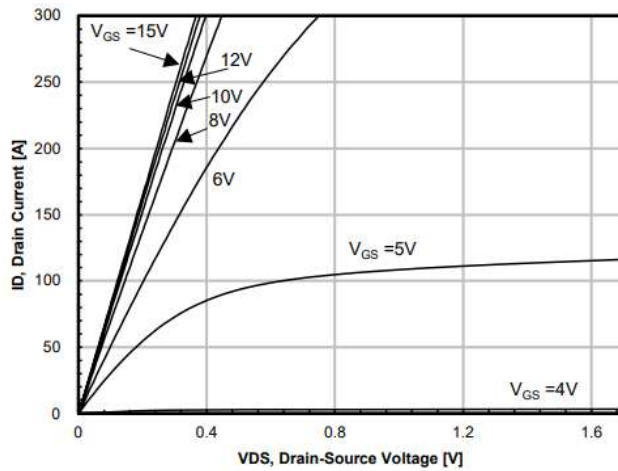


Fig. 1. On-Region Characteristics

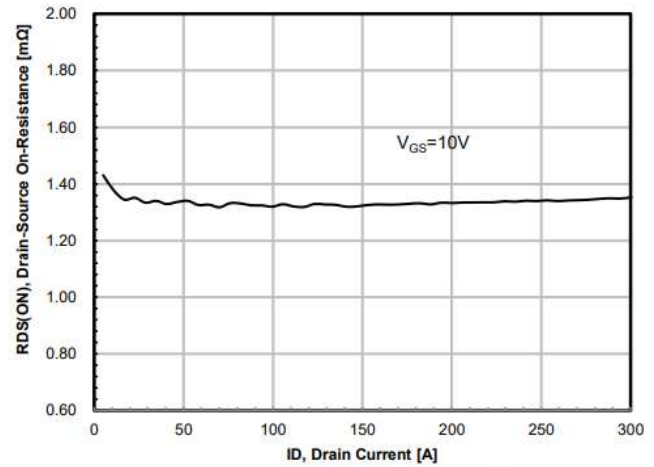


Fig. 2. On-Resistance vs. Drain Current and Gate Voltage

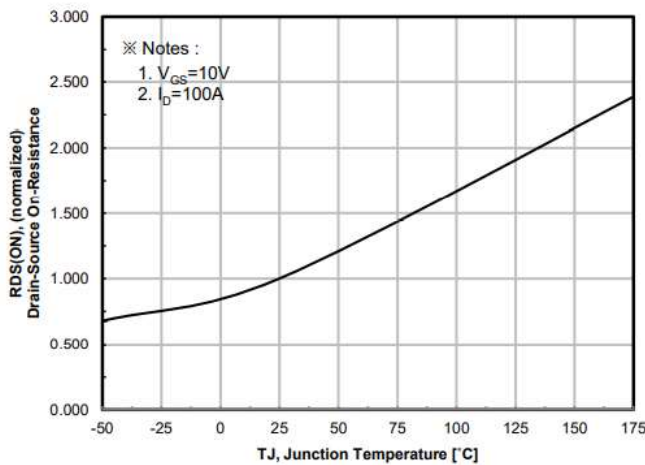


Fig. 3. On-Resistance vs. Junction Temperature

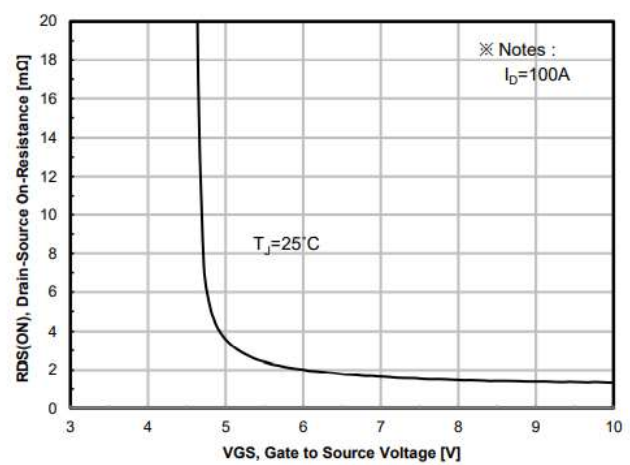


Fig. 4. On-Resistance vs. Gate to Source Voltage

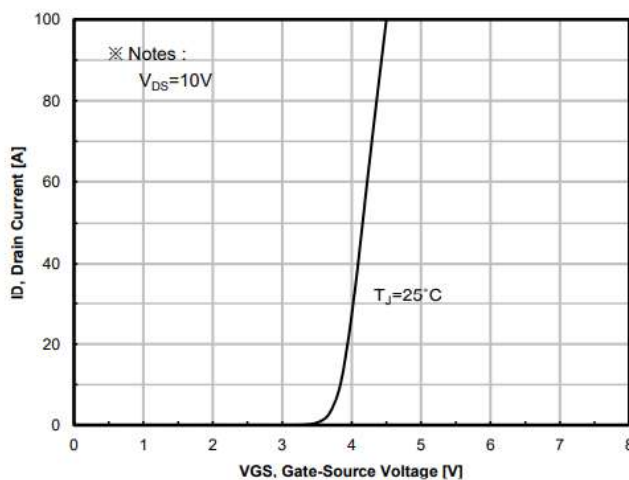


Fig. 5. Transfer Characteristics

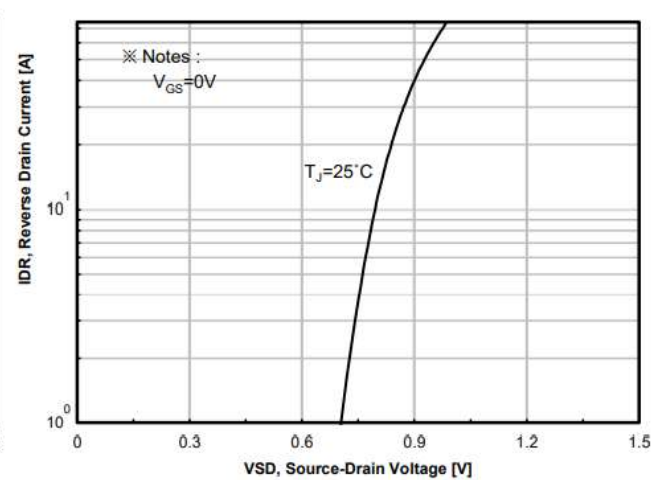


Fig. 6. Source-Drain Diode Forward Voltage

Electrical characteristics diagrams

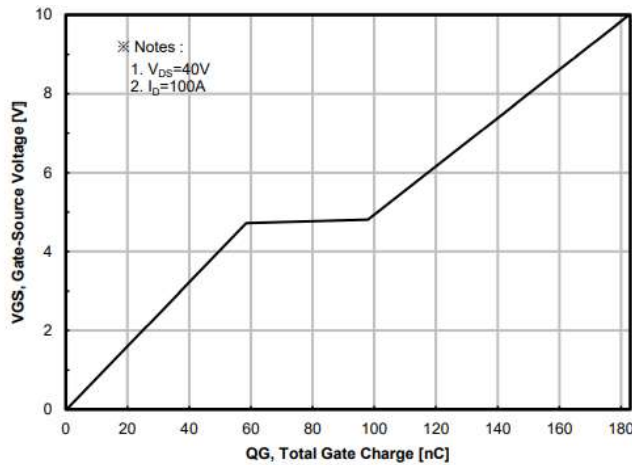


Fig. 7. Gate Charge

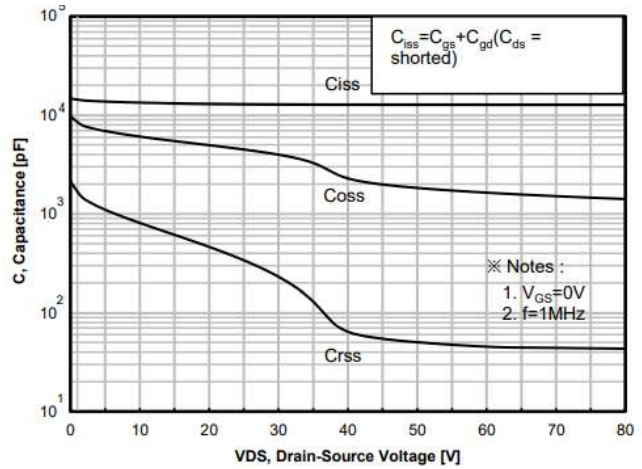


Fig. 8. Capacitance

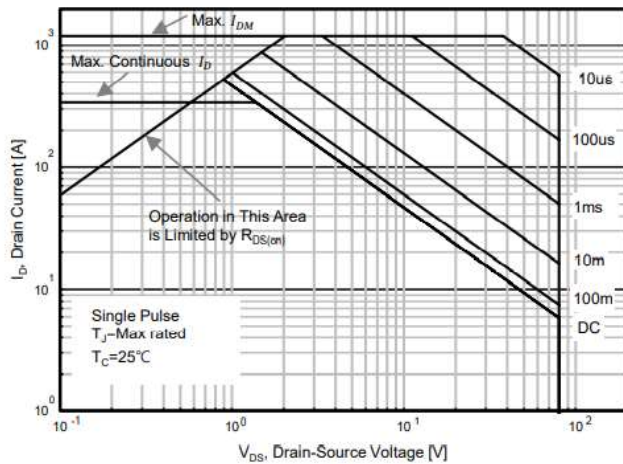


Fig. 9. Safe Operating Area, Junction-to-Ambient

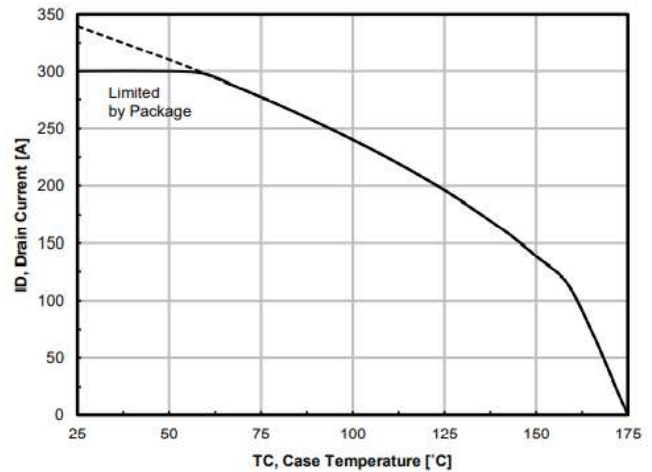


Fig. 10. Maximum Drain vs. Case Temperature

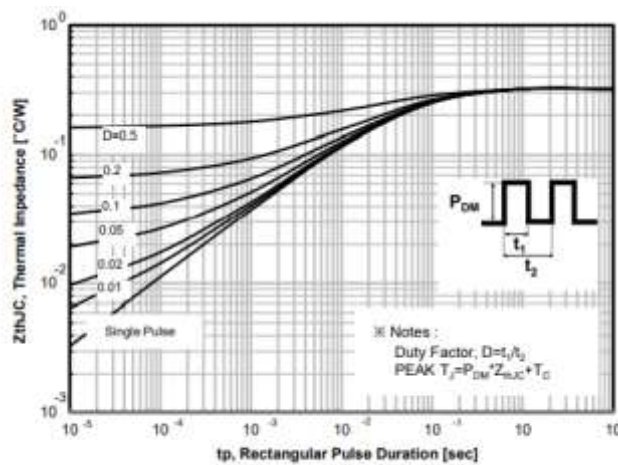
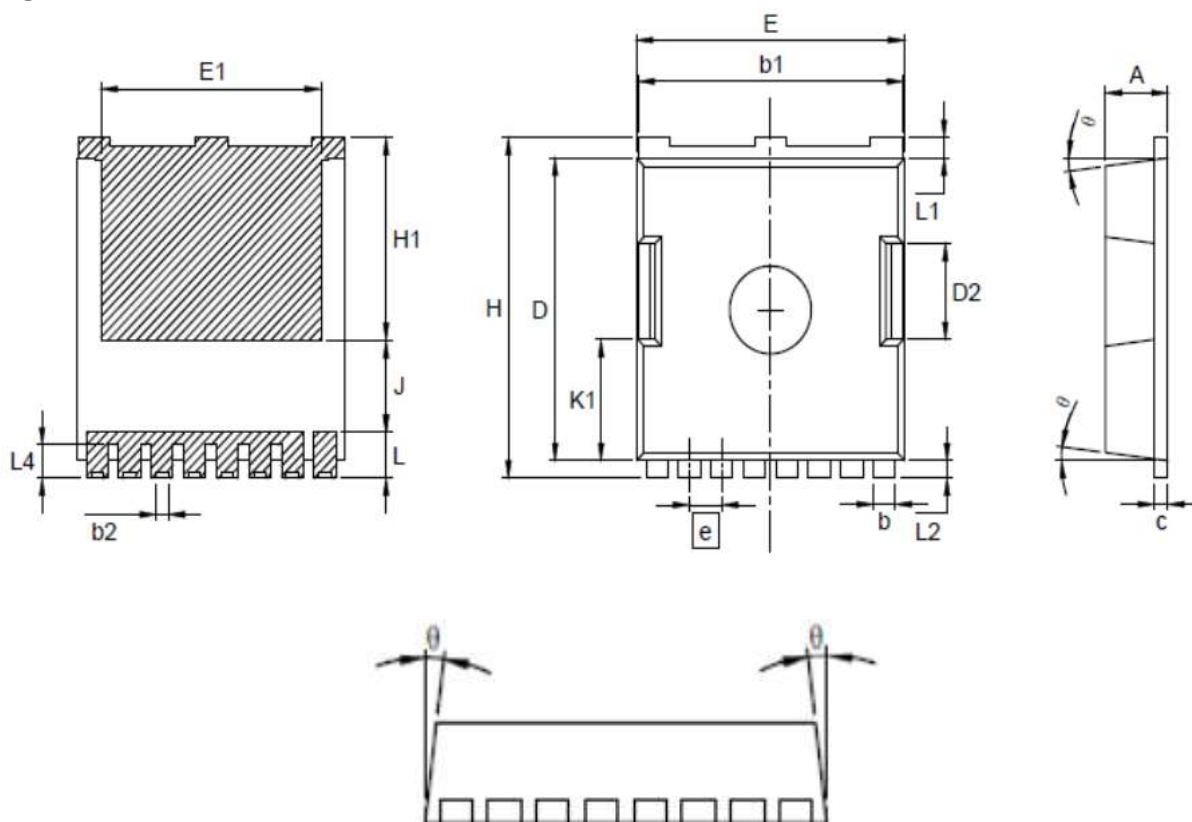


Fig. 11. Thermal Transient Impedance, Junction-to-Ambient

Package information

TOLL



Symbol	Dimension (mm)		
	Min	Nom	Max
A	2.20	—	2.40
b	0.70	—	0.90
b1	9.70	—	9.90
b2	0.37	—	0.50
c	0.40	—	0.60
D	10.28	—	10.58
D2	3.10	—	3.65
E	9.70	9.90	10.10
E1	7.70	8.00	8.30
e	BSC 1.20		
H	11.48	11.68	11.90
H1	6.75	—	7.15
J	2.80	—	3.30
K1	3.98	4.18	4.38
L	1.38	1.60	1.98
L1	0.60	0.70	0.80
L2	0.50	0.60	0.70
L4	1.00	1.15	1.30
Θ	4°	7°	10°